CARTES MÈRES

MEG Z690 UNIFY

THE WORLD RECORD BREAKER



SPECIFICATIONS

Model Name	MEG Z690 UNIFY
CPU Support	Supports 12th Gen Intel® Core™ Processors, Pentium® Gold and Celeron® Processors
CPU Socket	LGA 1700
Chipset	Intel® Z690 Chipset
Graphics Interface	2x PCIe 5.0 x16 slots 1x PCIe 3.0 x4 slot Support NVIDIA® SLI™ / AMD® CrossFire™ Technology
Memory Support	4 DIMMs, Dual Channel DDR5-6666+MHz(OC)
Storage	4x M.2 Gen4 x4 64Gbps slots, 1x M.2 Gen3 x4 32Gbps slot, 6x SATA 6Gb/s ports
USB ports	2x USB 3.2 Gen 2x2 20Gbps (2 Type-C), 7x USB 3.2 Gen 2 10Gbps (7 Type-A), 4x USB 3.2 Gen 1 5Gbps (4 Type-A), 6x USB 2.0
LAN	2x Intel® I225-V 2.5G LAN
Wireless / Bluetooth	Intel® Wi-Fi 6E module, Bluetooth 5.2
Audio	8-Channel (7.1) HD Audio with Audio Boost 5

FEATURES

Direct 19+2 Phases Power Design

Extreme direct power solution with 19+2 phases and 105A Smart Power Stage unleash the maximum CPU performance.

Latest DDR5 Memory

A huge step of DDR performance enhancement with the latest DDR5 memory and MSI Memory Boost technology.

Lightning Gen 5

The latest PCIe 5.0 solution with up to 128GB/s bandwidth for maximum transfer speed.

Quintuple M.2 Connectors

Onboard 5x M.2 connectors with quad PCIe 4.0 solution, strengthened by double-sided M.2 Shield Frozr.

Outstanding Cooling Solution

Aluminum Cover, VRM Heat-pipe, 7W/mK thermal pads, Double-sided M.2 Shield Frozr and Aluminum Backplate ensure the extreme performance with low temp.

Front and Rear Lightning USB 20G

USB 3.2 Gen 2x2 port offers 20Gbps transmission speed, 4x faster then USB 3.2 Gen 1, available when connecting the front and rear USB Type-C.

Dual 2.5G LAN

Onboard dual 2.5Gbps LAN with LAN manager provides incredible data transfer speed faster than general Gigabit LAN, delivering the best online gaming experience.

Wi-Fi 6E

La nouvelle solution de connexion sans-fil Wi-Fi 6 supporte le spectre 6 GHz, les technologies MU-MIMO et BSS et offre un débit allant jusqu'à 2400 Mb/s.

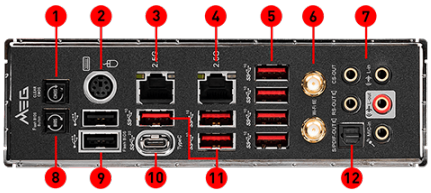
SMT PCIE and Memory Slot

The advanced SMT(Surface Mount Technology) welding process reduces the defect rate of slot solder joints, deliver the clean and pure signal.

8 Layer PCB with 2oz Thickened Copper

An Enhanced PCB design provides higher performance and long-lasting system stability without any compromise.

CONNECTIONS



1. Clear CMOS Button
2. PS/2 Keyboard / Mouse Port
3. 2.5G LAN
4. 2.5G LAN
5. USB 3.2 Gen 2 10Gbps (Type-A)
6. Wi-Fi / Bluetooth
7. HD Audio Connectors
8. Flash BIOS Button
9. USB 2.0
10. USB 3.2 Gen 2x2 20Gbps (Type-C)
11. USB 3.2 Gen 2 10Gbps (Type-A)
12. Optical S/PDIF-Out

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